MOSFETs Silicon N-channel MOS (U-MOSⅣ)

SSM3K347R

1. Applications

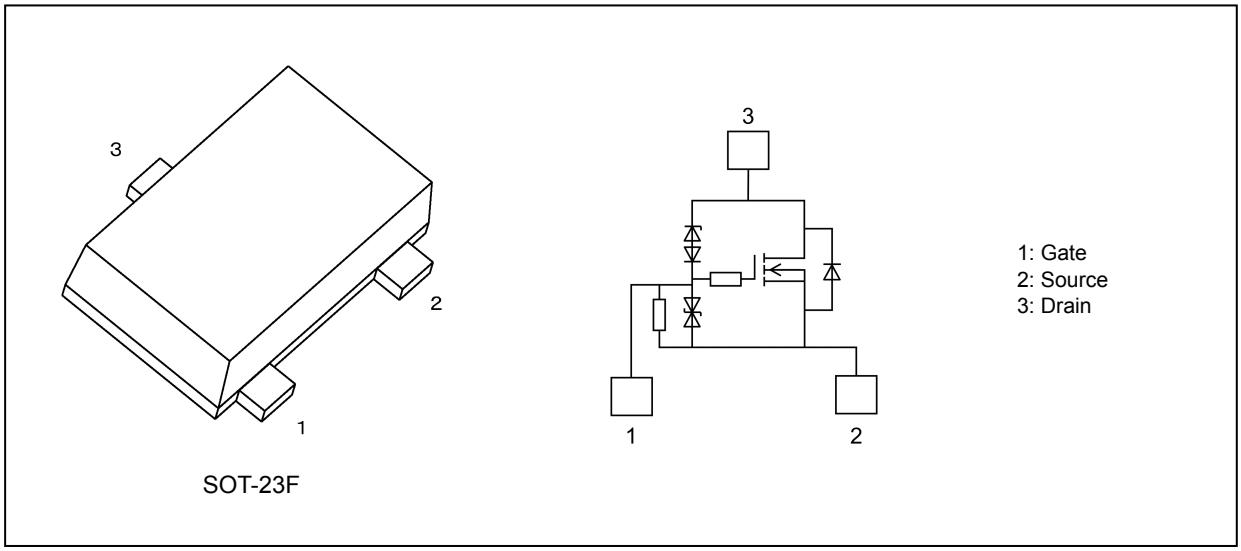
- Relay Drivers

2. Features

(1) AEC-Q101 (Rev. D) qualified. (Note 1)
(2) 4.0 V drive
(3) Built-in pull down resistance 47 kΩ.
(4) Low drain-source on-resistance
: $R_{DS(ON)}$ = 480 mΩ (max) (@V_{GS} = 4.0 V)
$R_{DS(ON)}$ = 410 mΩ (max) (@V_{GS} = 4.5 V)
$R_{DS(ON)}$ = 340 mΩ (max) (@V_{GS} = 10 V)

Note 1: For detail information, please contact our sales.

3. Packaging and Pin Assignment



Start of commercial production
2016-04

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4. Absolute Maximum Ratings (Note) (Unless otherwise specified, T_a = 25 °C)

Characteristics			Symbol	Rating	Unit
Drain-source voltage			$V_{DS(DC)}$	38	V
Gate-source voltage			V_{GSS}	±20	
Drain current (DC)		(Note 1)	I_D	2	A
Drain current (pulsed)		(Note 1), (Note 2)	I_{DP}	4	
Power dissipation		(Note 3)	P_D	1	W
Power dissipation	(t ≤ 10 s)	(Note 3)	P_D	2	
Channel temperature			T_{ch}	150	°C
Single-pulse active clamp capability		(Note 4)	E_{AS}	2.2	mJ
Storage temperature			T_{stg}	-55 to 150	°C

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.
Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

Note 1: Ensure that the channel temperature does not exceed 150 °C.

Note 2: pulse width ≤ 10 ms, Duty ≤ 1 %

Note 3: Device mounted on an FR4 board.(25.4 mm × 25.4 mm × 1.6 mm, Cu pad: 645 mm^2)

Note 4: V_{DD} = 25 V, T_{ch} = 25 °C (Initial state)

Note: The MOSFETs in this device are sensitive to electrostatic discharge. When handling this device, the worktables, operators, soldering irons and other objects should be protected against anti-static discharge.

Note: The channel-to-ambient thermal resistance, $R_{th(ch-a)}$, and the drain power dissipation, P_D, vary according to the board material, board area, board thickness and pad area. When using this device, be sure to take heat dissipation fully into account.

5. Thermal Characteristics

Characteristics		Symbol	Max	Unit
Channel-to-ambient thermal resistance	(Note 1)	$R_{th(ch-a)}$	125	°C/W

Note 1: Device mounted on an FR4 board.(25.4 mm × 25.4 mm × 1.6 mm, Cu pad: 645 mm^2)

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6. Electrical Characteristics

6.1. Static Characteristics (Unless otherwise specified, T_a = 25 °C)

Characteristics		Symbol	Test Condition	Min	Typ.	Max	Unit
Drain-source clamp voltage		$V_{(CL)DSS}$	I_D = 1 mA, V_{GS} = 0 V	38	43	48	V
Drain cut-off current		I_{DSS}	V_{DS} = 24 V, V_{GS} = 0 V	—	—	10	μA
Gate leakage current		I_{GSS}	V_{DS} = 0 V, V_{GS} = ±5 V	—	—	±152	
Gate threshold voltage	(Note 1)	V_{th}	V_{DS} = 10 V, I_D = 1 mA	1.4	—	2.4	V
Forward transfer admittance	(Note 2)	$\|Y_{fs}\|$	V_{DS} = 10 V, I_D = 1.0 A	—	4.1	—	S
Drain-source on-resistance	(Note 2)	$R_{DS(ON)}$	I_D = 0.5 A, V_{GS} = 4.0 V	—	350	480	mΩ
			I_D = 1.0 A, V_{GS} = 4.5 V	—	340	410	
			I_D = 1.0 A, V_{GS} = 10 V	—	280	340	
Pull-down resistance		R_{pd}	—	32.9	47	61.1	kΩ

Note 1: Let V_{th} be the voltage applied between gate and source that causes the drain current (I_D) to below (1 mA for this device). Then, for normal switching operation, $V_{GS(ON)}$ must be higher than V_{th}, and $V_{GS(OFF)}$ must be lower than V_{th}. This relationship can be expressed as: $V_{GS(OFF)} < V_{th} < V_{GS(ON)}$.
Take this into consideration when using the device.

Note 2: Pulse measurement.

6.2. Dynamic Characteristics (Unless otherwise specified, T_a = 25 °C)

Characteristics	Symbol	Test Condition	Min	Typ.	Max	Unit
Input capacitance	C_{iss}	V_{DS} = 10 V, V_{GS} = 0 V, f = 1 MHz	—	86	—	pF
Reverse transfer capacitance	C_{rss}		—	13	—	
Output capacitance	C_{oss}		—	27	—	
Switching time (turn-on time)	t_{on}	V_{DD} = 20 V, I_D = 0.5 A, V_{GS} = 0 to 4.5 V, R_{GS} = 50 Ω Duty ≤ 1 %, Input: t_r, t_f < 5 ns, Common source, See Chapter 6.3.	—	380	—	ns
Switching time (turn-off time)	t_{off}		—	800	—	

6.3. Switching Time Test Circuit

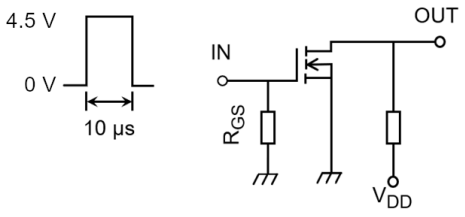


Fig. 6.3.1 Switching Time Test Circuit

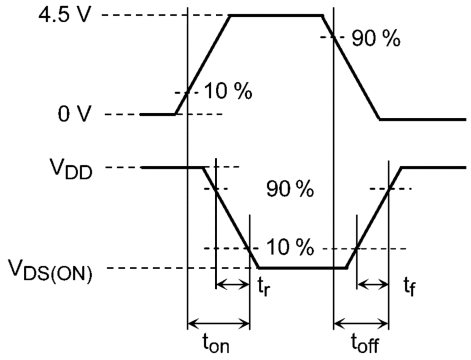


Fig. 6.3.2 Input Waveform/Output Waveform

6.4. Gate Charge Characteristics (Unless otherwise specified, T_a = 25 °C)

Characteristics	Symbol	Test Condition	Min	Typ.	Max	Unit
Total gate charge (gate-source plus gate-drain)	Q_g	V_{DD} = 20 V, I_D = 1.0 A, V_{GS} = 10 V	—	2.5	—	nC
Gate-source charge 1	Q_{gs1}		—	0.8	—	
Gate-drain charge	Q_{gd}		—	0.5	—	

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6.5. Source-Drain Characteristics (Unless otherwise specified, T_a = 25 °C)

Characteristics		Symbol	Test Condition	Min	Typ.	Max	Unit
Diode forward voltage	(Note 1)	V_{DSF}	I_{DR} = 2 A, V_{GS} = 0 V	—	0.87	1.2	V

Note 1: Pulse measurement.

7. Marking

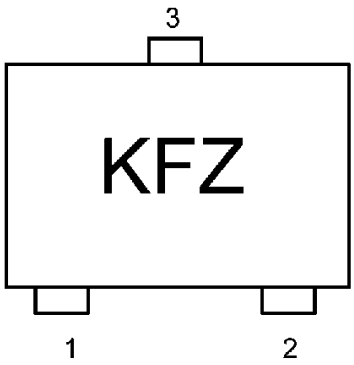


Fig. 7.1 Marking

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8. Characteristics Curves (Note)

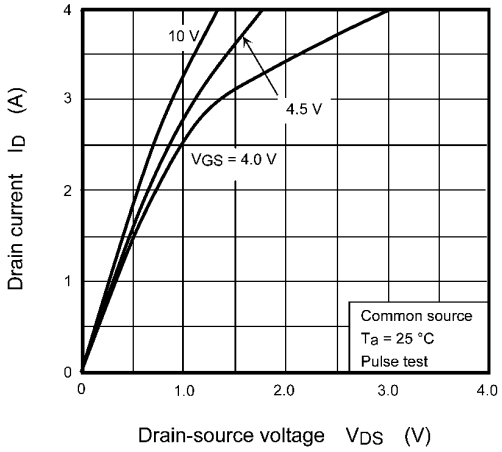


Fig. 8.1 I_D - V_{DS}

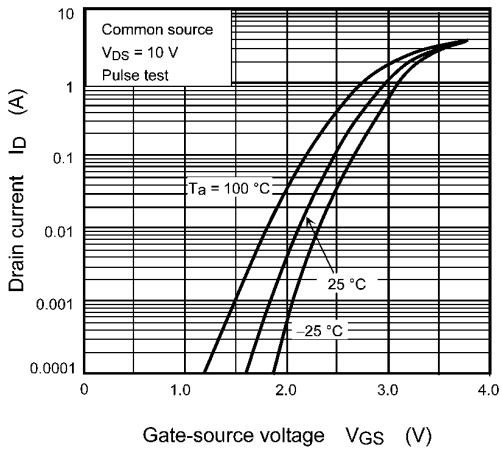


Fig. 8.2 I_D - V_{GS}

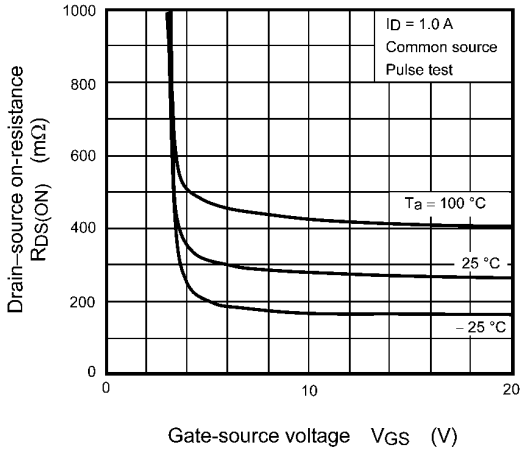


Fig. 8.3 $R_{DS(ON)}$ - V_{GS}

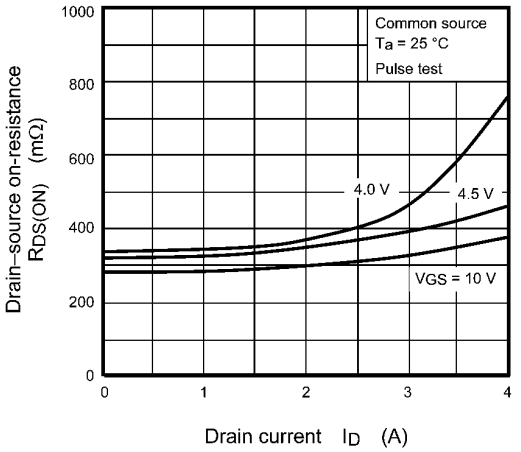


Fig. 8.4 $R_{DS(ON)}$ - I_D

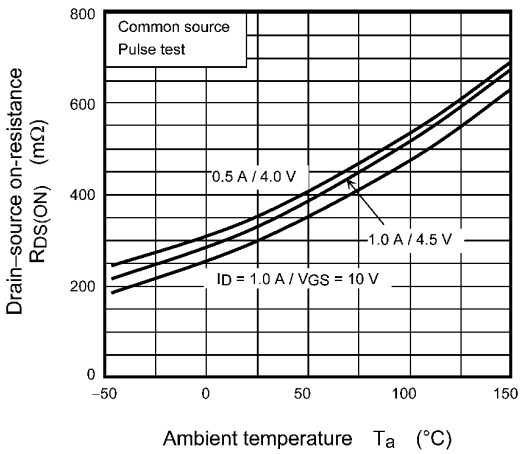


Fig. 8.5 $R_{DS(ON)}$ - T_a

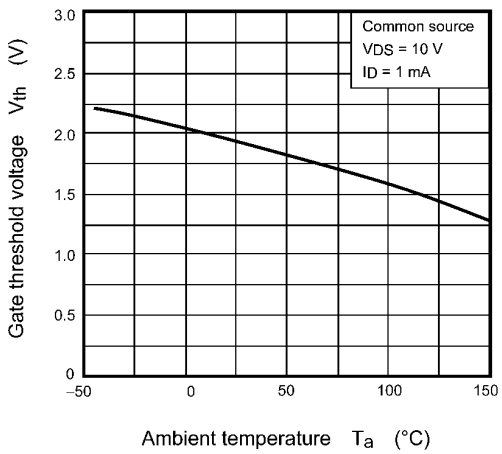


Fig. 8.6 V_{th} - T_a

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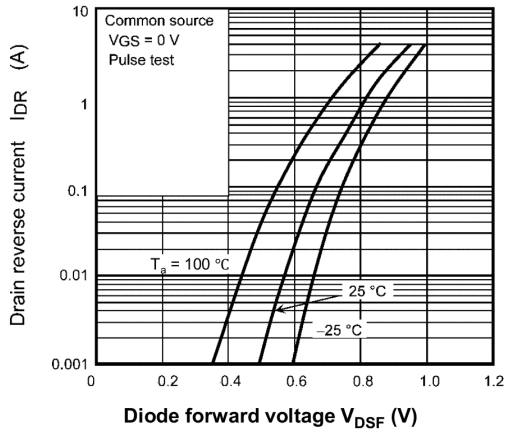


Fig. 8.7 I_{DR} - V_{DSF}

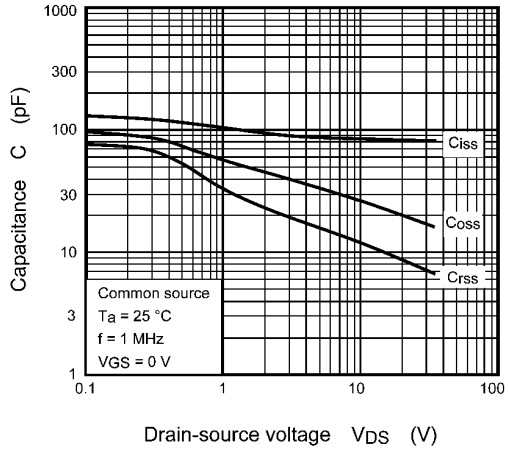


Fig. 8.8 C - V_{DS}

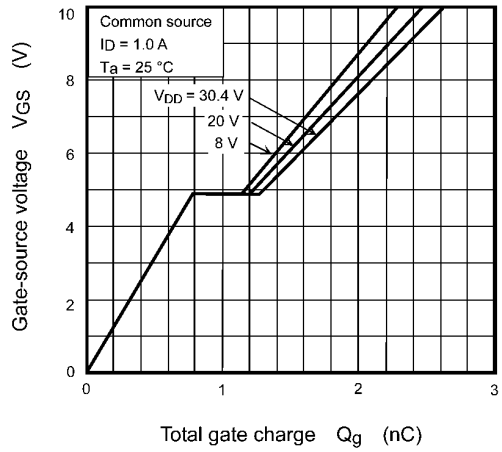


Fig. 8.9 Dynamic Input Characteristics

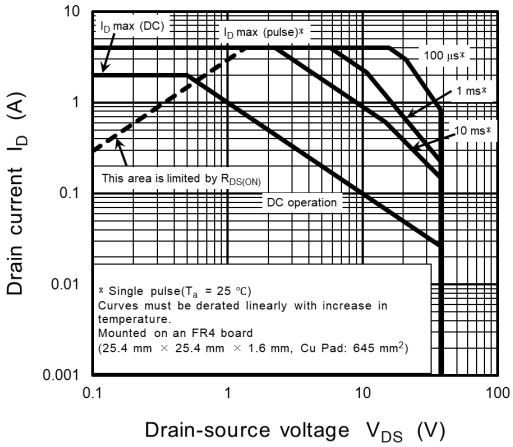


Fig. 8.10 Safe Operating Area

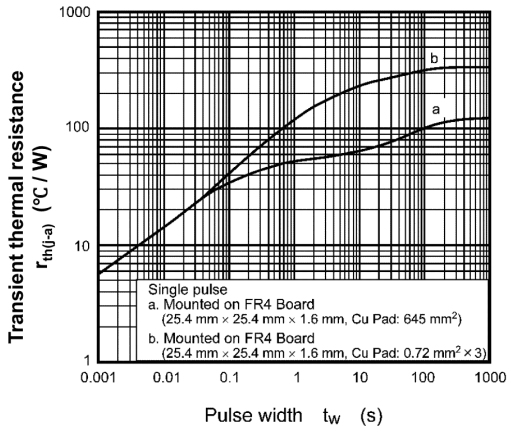


Fig. 8.11 $r_{th(j-a)}$ - t_w

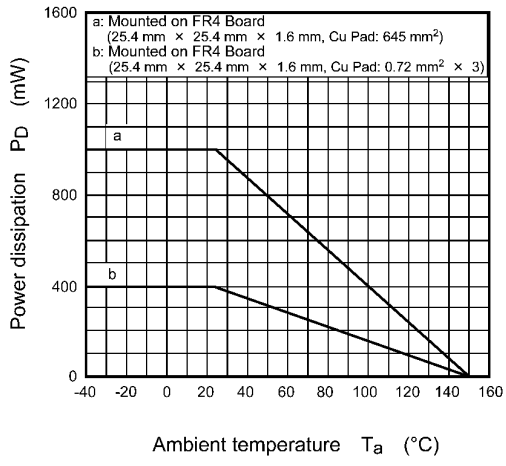


Fig. 8.12 P_D - T_a

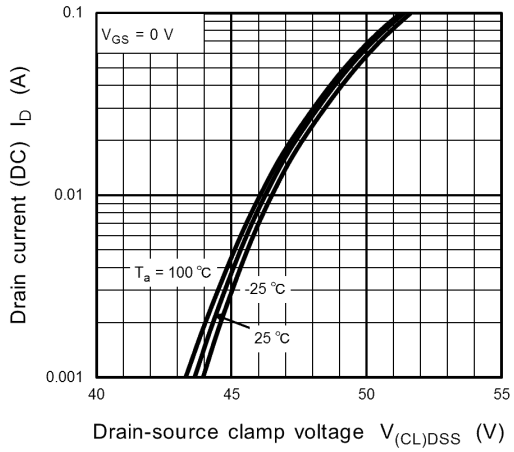
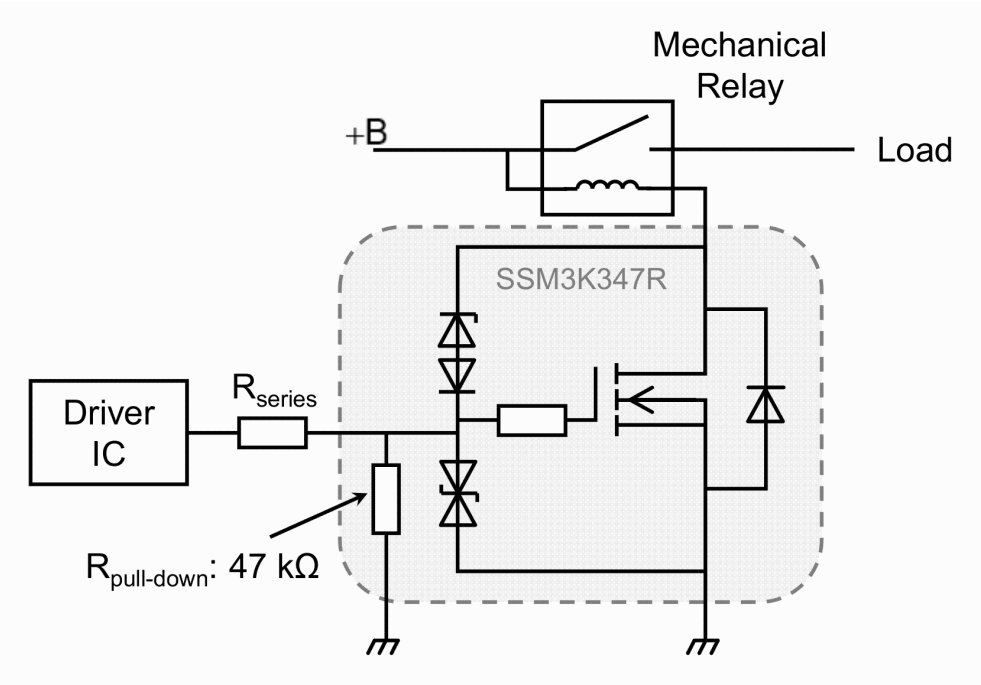


Fig. 8.13 I_D - $V_{(CL)DSS}$

Note: The above characteristics curves are presented for reference only and not guaranteed by production test, unless otherwise noted.

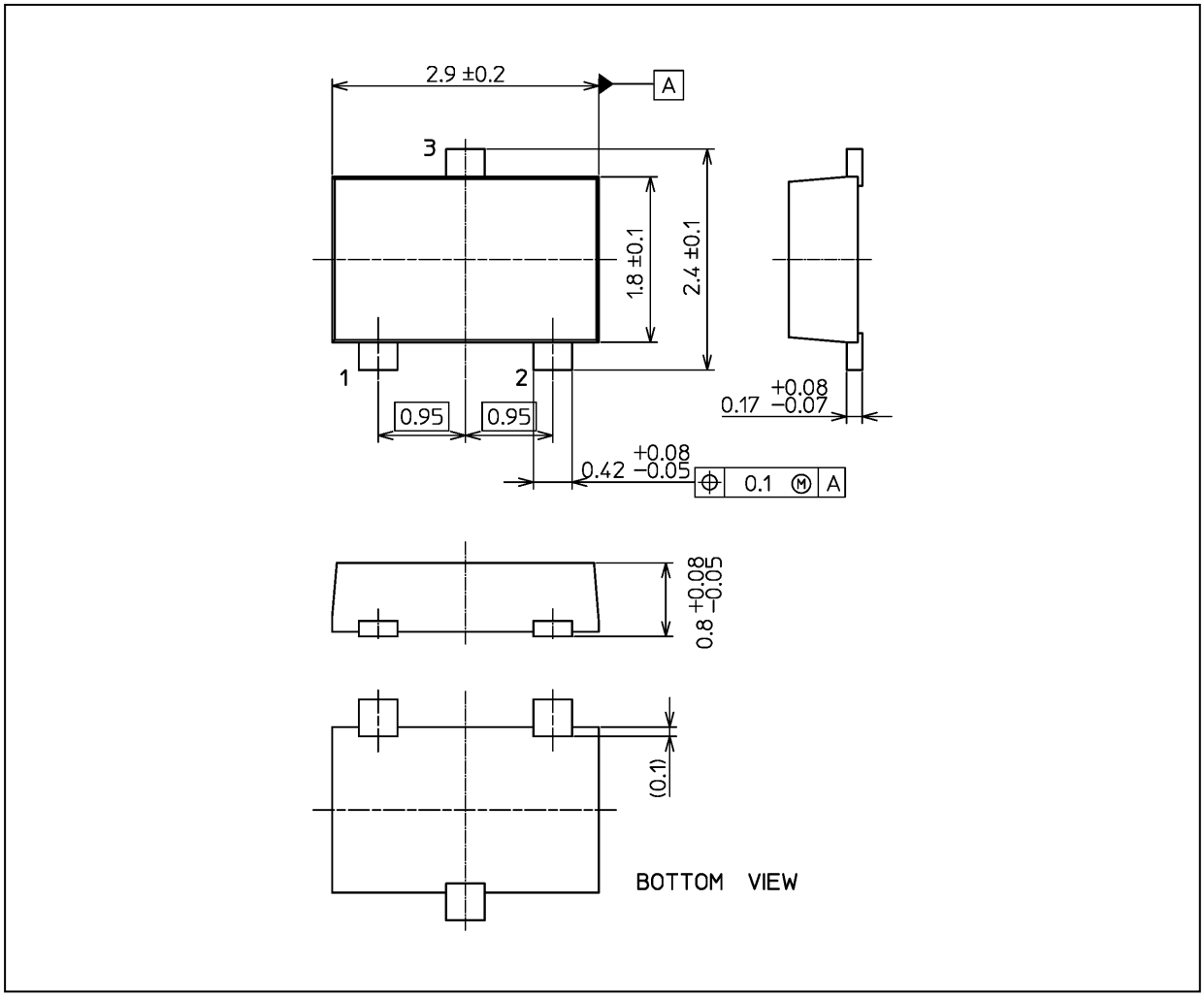
9. ACTIVE CLAMP APPLICATION



R_{series}:Input series resistance is necessary to set to a value.(range: 1 kΩ to 5 kΩ)

Package Dimensions

Unit: mm



Weight: 0.011 g (typ.)

Package Name(s)
Nickname: SOT-23F

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